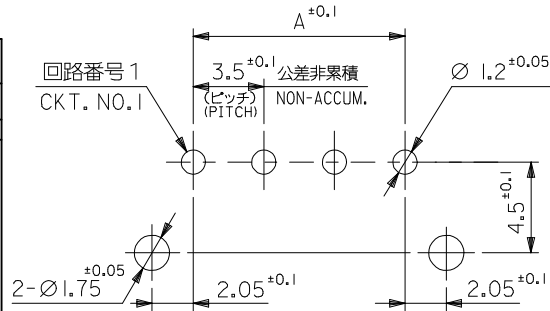
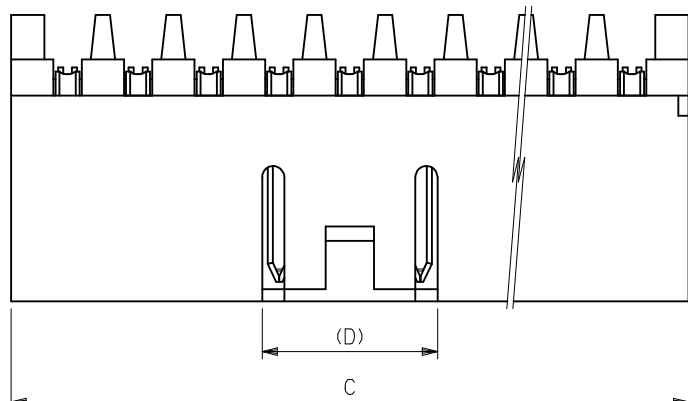
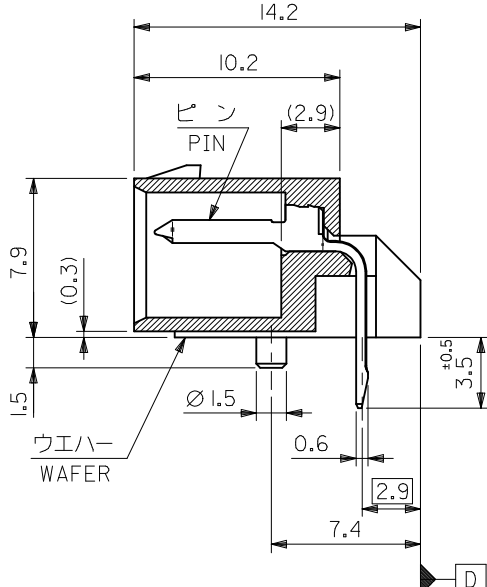
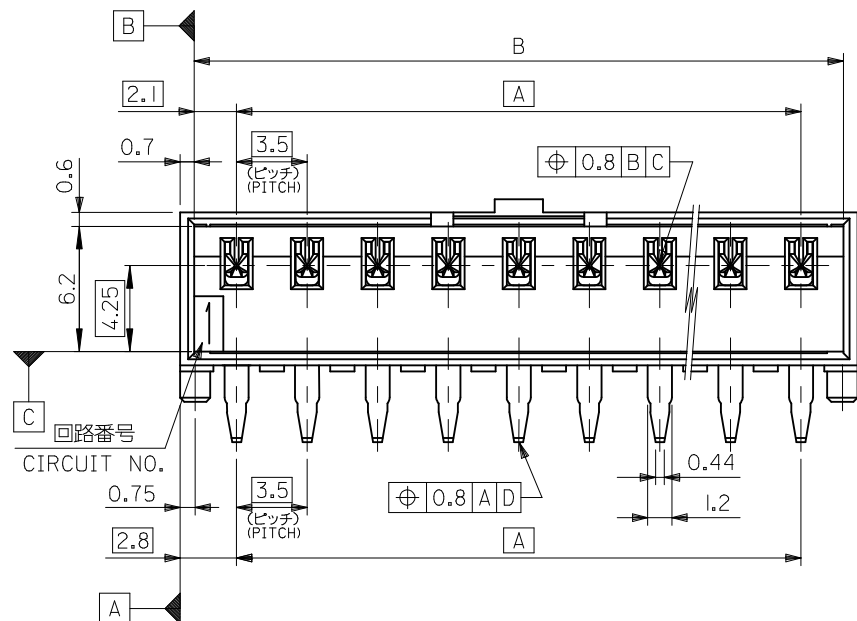


10 9 8 7 6 5 4 3 2 1



注記 NOTES

1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り) 、UL94V-0
WAFER : PBTP (G.F 15%) ,UL94V-0
ピン : 黄銅、ニッケル下地 鍍メッキ (t=0.254)
PIN : BRASS
TIN OVER NICKEL PLATING (t=0.254)
3. 本製品は 53259- **20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53259-**20.
4. メッキ仕様
TERMINAL PLATING
表面メッキ : スズメッキ 1μm MIN.
SURFACE PLATE : TIN 1μm MIN.
下地メッキ : ニッケルメッキ 1μm MIN.
UNDER PLATE : NICKEL 1μm MIN.



8.7	54.6	53.2	49.0	53259-1529	15
	51.1	49.7	45.5	-1429	14
	47.6	46.2	42.0	-1329	13
	44.1	42.7	38.5	-1229	12
	40.6	39.2	35.0	-1129	11
	37.1	35.7	31.5	-1029	10
	33.6	32.2	28.0	-0929	9
	30.1	28.7	24.5	-0829	8
	26.6	25.2	21.0	-0729	7
	23.1	21.7	17.5	-0629	6
	19.6	18.2	14.0	-0529	5
8.7	16.1	14.7	10.5	-0429	4
6.1	12.6	11.2	7.0	-0329	3
6.1	9.1	7.7	3.5	53259-0229	2
(D)	C	B	A	TRAY PACKAGE	CKT. 極数
				ORDER No. オータ-番号	

REVISED EC NO: J2010-0817 DRWN:SKUROSE 2009/10/22 CHKD:KASAKAWA 2009/10/22 APPR:NUK ITA 2009/10/22 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1		DESIGN UNITS METRIC		MODEL NO. 53259-**29		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE						
	10 OVER 30 UNDER	±0.25	T. UENO	2004/04/22	3.5 W/B CONN						
	30 OVER	±0.3	CHECKED BY	DATE	W.A. R/A						
		M. SASAO	2004/04/22	-LEAD FREE-							
		APPROVED BY	DATE	MOLEX MOLEX INCORPORATED							
		M. SASAO	2004/04/22	DOCUMENT NO. SD-53259-003							
		MATERIAL NO.		SEE TABLE		SHEET NO. 1 OF 1					
		ANGULAR ±3 °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

MATERIAL 材料
注記参照
SEE NOTES